

Global Flip Chip CSP (FCCSP) Package Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

<https://marketpublishers.com/r/F0D1E15F7A27EN.html>

Date: July 2025

Pages: 115

Price: US\$ 3,480.00 (Single User License)

ID: F0D1E15F7A27EN

Abstracts

According to our (Global Info Research) latest study, the global Flip Chip CSP (FCCSP) Package market size was valued at US\$ million in 2024 and is forecast to a readjusted size of USD million by 2031 with a CAGR of %during review period.

FCCSP (Flip Chip Chip Scale Package) offers chip scale capacity for I/Os around 200 or less. FCCSP provides better protection for chip and better solder joint reliability compared with direct chip attach (DCA) or chip on board (COB). FCCSP is more superior to known good die (KGD) in low-cost test and burn-in, and performs comparable electrical function with KGD. FCCSP features thin and small profile, and lightweight packages.

The global market for semiconductor was estimated at US\$ 579 billion in the year 2022, is projected to US\$ 790 billion by 2029, growing at a CAGR of 6% during the forecast period. Although some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.76%, Sensor with 16.31%, and Logic with 14.46% growth, Memory declined with 12.64% year over year. The microprocessor (MPU) and microcontroller (MCU) segments will experience stagnant growth due to weak shipments and investment in notebooks, computers, and standard desktops. In the current market scenario, the growing popularity of IoT-based electronics is stimulating the need for powerful processors and controllers. Hybrid MPUs and MCUs provide real-time embedded processing and control for the topmost IoT-based applications, resulting in significant market growth. The Analog IC segment is expected to grow gradually, while demand from the networking and communications industries is limited. Few of the emerging trends in the growing demand for Analog integrated circuits include signal conversion, automotive-specific Analog applications, and power management. They

drive the growing demand for discrete power devices.

This report is a detailed and comprehensive analysis for global Flip Chip CSP (FCCSP) Package market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Flip Chip CSP (FCCSP) Package market size and forecasts, in consumption value (\$ Million), sales quantity (K Units), and average selling prices (US\$/Unit), 2020-2031

Global Flip Chip CSP (FCCSP) Package market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (K Units), and average selling prices (US\$/Unit), 2020-2031

Global Flip Chip CSP (FCCSP) Package market size and forecasts, by Type and by Application, in consumption value (\$ Million), sales quantity (K Units), and average selling prices (US\$/Unit), 2020-2031

Global Flip Chip CSP (FCCSP) Package market shares of main players, shipments in revenue (\$ Million), sales quantity (K Units), and ASP (US\$/Unit), 2020-2025

The Primary Objectives in This Report Are:

- To determine the size of the total market opportunity of global and key countries
- To assess the growth potential for Flip Chip CSP (FCCSP) Package
- To forecast future growth in each product and end-use market
- To forecast future factors affecting the marketplace

This report profiles key players in the global Flip Chip CSP (FCCSP) Package market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Amkor, Taiwan Semiconductor Manufacturing, ASE Group, Intel Corporation, JCET Group Co.,Ltd, Samsung Group,

SPIL, Powertech Technology, Tongfu Microelectronics Co., Ltd, Tianshui Huatian Technology Co., Ltd, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Flip Chip CSP (FCCSP) Package market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Bare Die Type

Molded (CUF, MUF) Type

SiP Type

Hybrid (fcSCSP) Type

Others

Market segment by Application

Auto and Transportation

Consumer Electronics

Communication

Others

Major players covered

Amkor

Taiwan Semiconductor Manufacturing

ASE Group

Intel Corporation

JCET Group Co.,Ltd

Samsung Group

SPIL

Powertech Technology

Tongfu Microelectronics Co., Ltd

Tianshui Huatian Technology Co., Ltd

United Microelectronics

SFA Semicon

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Flip Chip CSP (FCCSP) Package product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Flip Chip CSP (FCCSP) Package, with

Global Flip Chip CSP (FCCSP) Package Market 2025 by Manufacturers, Regions, Type and Application, Forecast to...

price, sales quantity, revenue, and global market share of Flip Chip CSP (FCCSP) Package from 2020 to 2025.

Chapter 3, the Flip Chip CSP (FCCSP) Package competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Flip Chip CSP (FCCSP) Package breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025. and Flip Chip CSP (FCCSP) Package market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Flip Chip CSP (FCCSP) Package.

Chapter 14 and 15, to describe Flip Chip CSP (FCCSP) Package sales channel, distributors, customers, research findings and conclusion.

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